505803873 12/04/2019

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
YU-CHIEH CHOU	11/21/2019
HSIN-CHIH LIN	11/21/2019

RECEIVING PARTY DATA

Name:	VANGUARD INTERNATIONAL SEMICONDUCTOR CORPORATION	
Street Address:	123, PARK AVE-3RD, HSINCHU SCIENCE PARK	
City:	HSINCHU	
State/Country:	TAIWAN	
Postal Code:	30077	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16702078

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	0941-4146PUS1	
NAME OF SUBMITTER:	OF SUBMITTER: MICHAEL A CLEMENTI	
SIGNATURE:	/Michael A Clementi/	
DATE SIGNED:	12/04/2019	

Total Attachments: 2

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PATENT 505803873 REEL: 051181 FRAME: 0309

ASSIGNMENT

WHEREAS, Yu-Chieh CHOU and Hsin-Chih LIN hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent: Title: SEMICONDUCTOR DEVICES AND METHODS OF MANUFACTURING THE SAME				
Filed: 12/3/2019 Serial No. 16/702,078 Executed on: 11/21/2019				
WHEREAS, Vanguard International Semiconductor Corporation of 123, Park Ave-3rd, Science - Based Industrial Park, Hsinchu, Taiwan 30077, R.O.C. hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;				
NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.				
Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.				
IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.				
Yu-Chieh CHOU Date Date				
Hsin-Chih LIN Date				

ASSIGNMENT

WHEREAS, Yu-Chieh CHOU and Hsin-Chih LIN hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:				
Title: SEMICONDUCTOR DEVICES AND METHODS OF MANUFACTURING THE SAME				
Filed: Seria	l No.			

WHEREAS, Vanguard Internation of 123, Park Ave-3rd, Science - Ba Taiwan 30077, R.O.C. hereinafter referred ASSIGNOR'S interest in the said invention and which may be granted on the same; NOW, THEREFORE, TO ALL WHOM IT	sed Industrial Park, Hsinchu, l to as ASSIGNEE, is desirous of acquiring application and in any U.S. Letters Patent			
NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assigner had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.				
Assignor further agrees/agree that he Assignee, but at Assignee's expense, cooperate application and/or applications, execute, verify, papers, including applications for Letters Patent at of assignment and transfer thereof, and will perform request, to obtain or maintain Letters Patent is vest title thereto in said Assignee, or Assignee's sur	acknowledge and deliver all such further and for the reissue thereof, and instruments form such other acts as Assignee lawfully for said invention and improvement, and to			
IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.				
Yu-Chieh CHOU	Date			
Hein Chih L. Hein-Chih LIN	2019. 11. 4 Date			
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PATENT REEL: 051181 FRAME: 0311

RECORDED: 12/04/2019